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### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	I <sup>2</sup> C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	<a href="https://www.e-xfl.com/product-detail/stmicroelectronics/st72f321bar6tae">https://www.e-xfl.com/product-detail/stmicroelectronics/st72f321bar6tae</a>

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## 6.5 Reset sequence manager (RSM)

### 6.5.1 Introduction

The reset sequence manager includes three RESET sources as shown in [Figure 11](#):

- External RESET source pulse
- Internal LVD RESET (low voltage detection)
- Internal WATCHDOG RESET

These sources act on the  $\overline{\text{RESET}}$  pin and it is always kept low during the delay phase.

The RESET service routine vector is fixed at addresses FFFEh-FFFFh in the ST7 memory map.

The basic RESET sequence consists of three phases as shown in [Figure 12](#):

- Active phase depending on the RESET source
- 256 or 4096 CPU clock cycle delay (selected by option byte)
- RESET vector fetch

**Caution:** When the ST7 is unprogrammed or fully erased, the Flash is blank and the RESET vector is not programmed. For this reason, it is recommended to keep the  $\overline{\text{RESET}}$  pin in low state until programming mode is entered, in order to avoid unwanted behavior.

The 256 or 4096 CPU clock cycle delay allows the oscillator to stabilize and ensures that recovery has taken place from the Reset state. The shorter or longer clock cycle delay should be selected by option byte to correspond to the stabilization time of the external oscillator used in the application (see [Section 21.1.1: Flash configuration on page 225](#)).

The RESET vector fetch phase duration is 2 clock cycles.

**Figure 11. Reset block diagram**

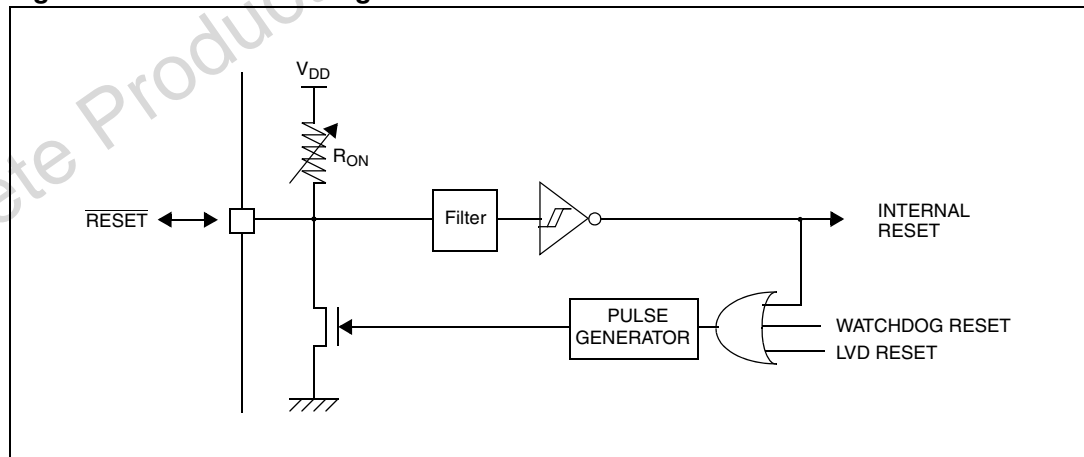
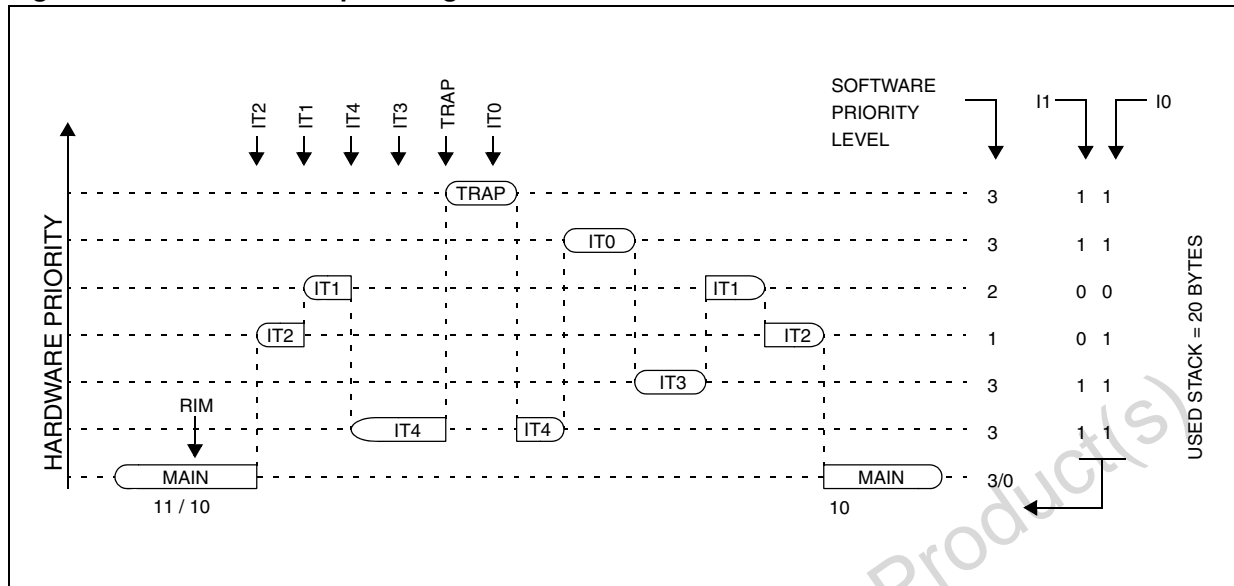


Figure 20. Nested interrupt management



## 7.5 Interrupt register description

### 7.5.1 CPU CC register interrupt bits

CPU CC					Reset value: 111x 1010 (xAh)		
7	6	5	4	3	2	1	0
1	1	I1	H	I0	N	Z	C
		RW	RW	RW	RW	RW	RW

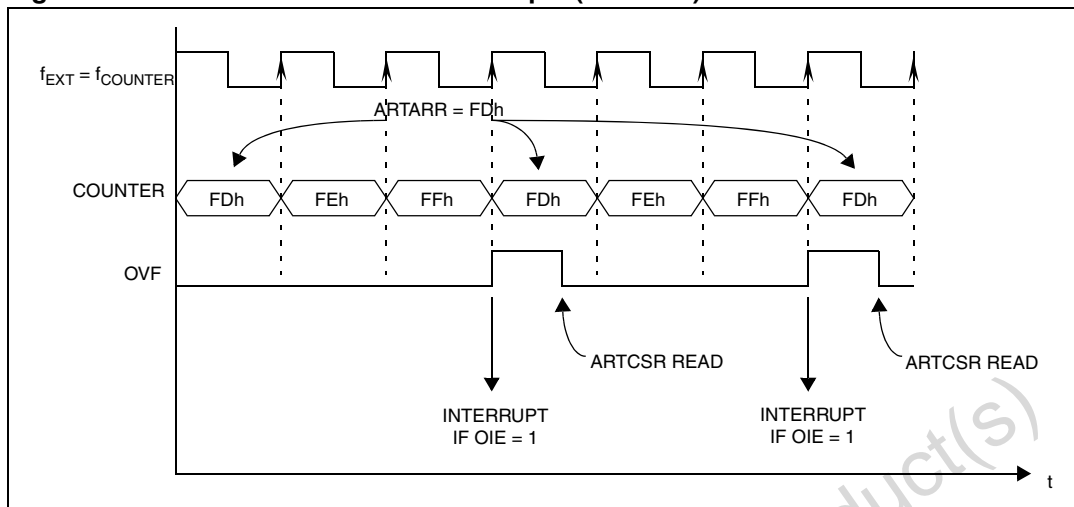
Table 15. CPU CC register interrupt bits description

Bit	Name	Function
5	I1	Interrupt Software Priority 1
3	I0	Interrupt Software Priority 0

These two bits indicate the current interrupt software priority (see [Table 16](#)) and are set/cleared by hardware when entering in interrupt. The loaded value is given by the corresponding bits in the interrupt software priority registers (ISPRx).

They can be also set/cleared by software with the RIM, SIM, HALT, WFI, IRET and PUSH/POP instructions (see [Table 18: Interrupt dedicated instruction set](#)).

Figure 39. External event detector example (3 counts)



### 12.2.8 Input capture function

This mode allows the measurement of external signal pulse widths through ARTICRx registers.

Each input capture can generate an interrupt independently on a selected input signal transition. This event is flagged by a set of the corresponding CFx bits of the Input Capture Control/Status register (ARTICCSR).

These input capture interrupts are enabled through the CIEx bits of the ARTICCSR register.

The active transition (falling or rising edge) is software programmable through the CSx bits of the ARTICCSR register.

The read only input capture registers (ARTICRx) are used to latch the auto-reload counter value when a transition is detected on the ARTICx pin (CFx bit set in ARTICCSR register). After fetching the interrupt vector, the CFx flags can be read to identify the interrupt source.

*Note:* After a capture detection, data transfer in the ARTICRx register is inhibited until it is read (clearing the CFx bit).

The timer interrupt remains pending while the CFx flag is set when the interrupt is enabled (CIEx bit set). This means that the ARTICRx register has to be read at each capture event to clear the CFx flag.

The timing resolution is given by auto-reload counter cycle time ( $1/f_{\text{COUNTER}}$ ).

*Note:* During Halt mode, if both the input capture and the external clock are enabled, the ARTICRx register value is not guaranteed if the input capture pin and the external clock change simultaneously.

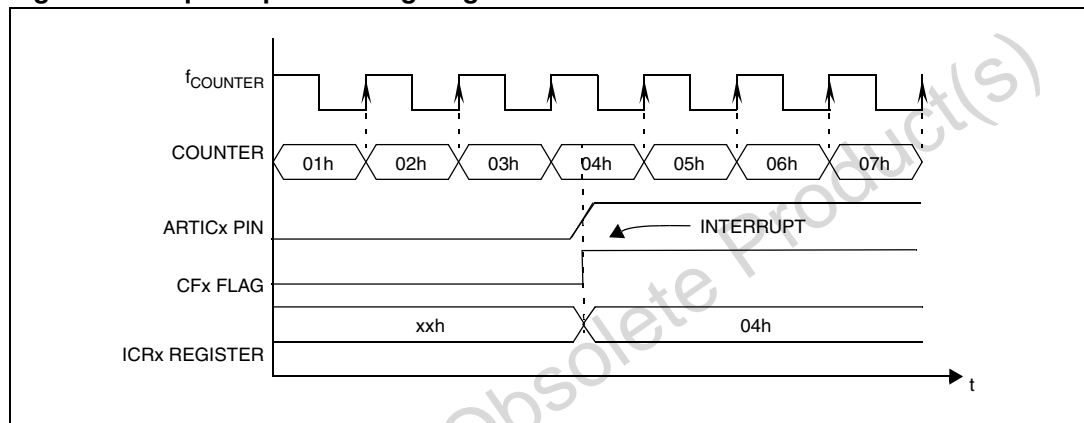
### 12.2.9 External interrupt capability

This mode allows the input capture capabilities to be used as external interrupt sources. The interrupts are generated on the edge of the ARTICx signal.

The edge sensitivity of the external interrupts is programmable (CSx bit of ARTICCSR register) and they are independently enabled through CIEx bits of the ARTICCSR register. After fetching the interrupt vector, the CFx flags can be read to identify the interrupt source.

During Halt mode, the external interrupts can be used to wake up the micro (if the CIEx bit is set).

**Figure 40. Input capture timing diagram**



### 13.3.6 One Pulse mode

One Pulse mode enables the generation of a pulse when an external event occurs. This mode is selected via the OPM bit in the CR2 register.

The one pulse mode uses the Input Capture1 function and the Output Compare1 function.

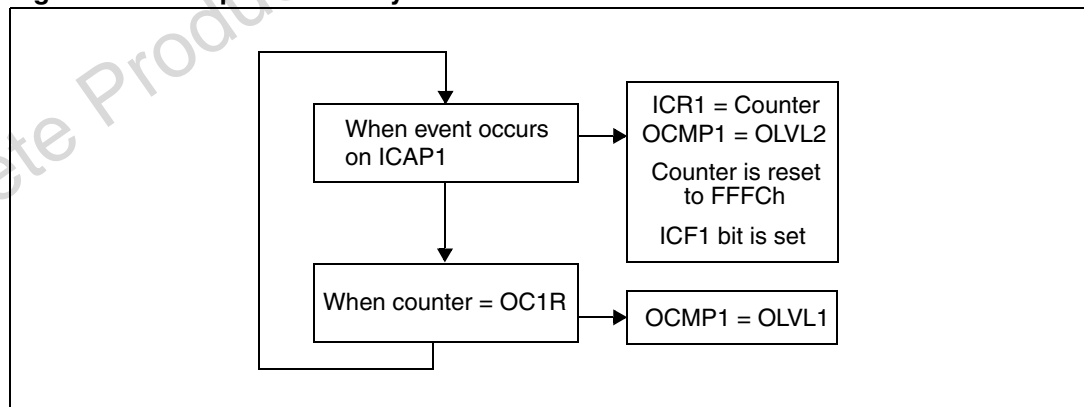
#### Procedure

To use one pulse mode:

1. Load the OC1R register with the value corresponding to the length of the pulse (using the appropriate formula below according to the timer clock source used).
2. Select the following in the CR1 register:
  - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after the pulse.
  - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin during the pulse.
  - Select the edge of the active transition on the ICAP1 pin with the IEDG1 bit (the ICAP1 pin must be configured as floating input).
3. Select the following in the CR2 register:
  - Set the OC1E bit, the OCMP1 pin is then dedicated to the Output Compare 1 function.
  - Set the OPM bit.
  - Select the timer clock CC[1:0] (see [Table 60: Timer clock selection](#)).

Then, on a valid event on the ICAP1 pin, the counter is initialized to FFFCh and OLVL2 bit is loaded on the OCMP1 pin, the ICF1 bit is set and the value FFFDh is loaded in the IC1R register.

**Figure 51. One pulse mode cycle flowchart**



Because the ICF1 bit is set when an active edge occurs, an interrupt can be generated if the ICIE bit is set.

Clearing the input capture interrupt request (that is, clearing the ICF $i$  bit) is done in two steps:

1. Reading the SR register while the ICF $i$  bit is set
2. An access (read or write) to the IC $i$ LR register



The OC1R register value required for a specific timing application can be calculated using the following formula:

$$OC1R \text{ value} = \frac{t * f_{CPU} - 5}{PRESC}$$

Where:

- t = Pulse period (in seconds)
- f<sub>CPU</sub> = CPU clock frequency (in hertz)
- PRESC = Timer prescaler factor (2, 4 or 8 depending on the CC[1:0] bits; see [Table 60: Timer clock selection](#))

If the timer clock is an external clock the formula is:

$$OC1R = t * f_{EXT} - 5$$

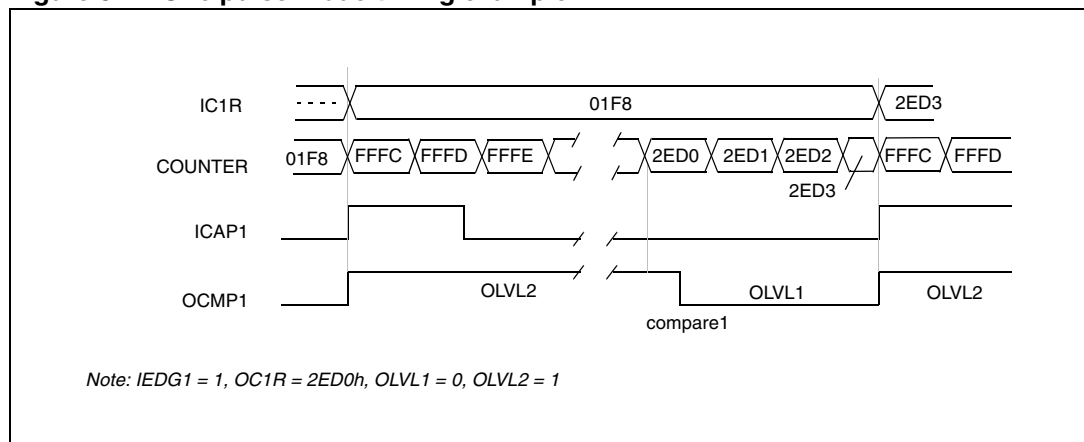
Where:

- t = Pulse period (in seconds)
- f<sub>EXT</sub> = External clock frequency (in hertz)

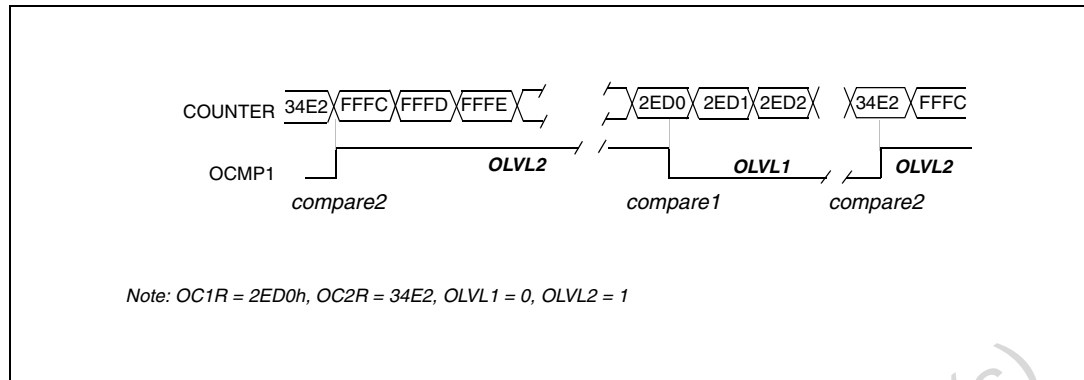
When the value of the counter is equal to the value of the contents of the OC1R register, the OLVL1 bit is output on the OCMP1 pin (see [Figure 52](#)).

- Note:*
- 1 The OCF1 bit cannot be set by hardware in one pulse mode but the OCF2 bit can generate an Output Compare interrupt.
  - 2 When the Pulse Width Modulation (PWM) and One Pulse Mode (OPM) bits are both set, the PWM mode is the only active one.
  - 3 If OLVL1 = OLVL2 a continuous signal will be seen on the OCMP1 pin.
  - 4 The ICAP1 pin cannot be used to perform input capture. The ICAP2 pin can be used to perform input capture (ICF2 can be set and IC2R can be loaded) but the user must take care that the counter is reset each time a valid edge occurs on the ICAP1 pin and ICF1 can also generate interrupt if ICIE is set.
  - 5 When one pulse mode is used OC1R is dedicated to this mode. Nevertheless OC2R and OCF2 can be used to indicate a period of time has been elapsed but cannot generate an output waveform because the level OLVL2 is dedicated to the one pulse mode.

**Figure 52. One pulse mode timing example**



**Figure 53. Pulse width modulation mode timing example with 2 output compare functions**



*Note:* On timers with only one Output Compare register, a fixed frequency PWM signal can be generated using the output compare and the counter overflow to define the pulse length.

### 13.3.7 Pulse width modulation mode

Pulse Width Modulation (PWM) mode enables the generation of a signal with a frequency and pulse length determined by the value of the OC1R and OC2R registers.

Pulse Width Modulation mode uses the complete Output Compare 1 function plus the OC2R register, and so this functionality cannot be used when PWM mode is activated.

In PWM mode, double buffering is implemented on the output compare registers. Any new values written in the OC1R and OC2R registers are taken into account only at the end of the PWM period (OC2) to avoid spikes on the PWM output pin (OCMP1).

#### Procedure

To use pulse width modulation mode:

1. Load the OC2R register with the value corresponding to the period of the signal using the appropriate formula below according to the timer clock source used.
2. Load the OC1R register with the value corresponding to the period of the pulse if OLVL1 = 0 and OLVL2 = 1 using the appropriate formula below according to the timer clock source used.
3. Select the following in the CR1 register:
  - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC1R register.
  - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC2R register.
4. Select the following in the CR2 register:
  - Set OC1E bit: the OCMP1 pin is then dedicated to the output compare 1 function.
  - Set the PWM bit.
  - Select the timer clock (CC[1:0]) (see [Table 60: Timer clock selection](#)).

**Table 71. SCI interrupt control/wake-up capability**

Interrupt event	Event flag	Enable control bit	Exit from Wait	Exit from Halt
Idle Line Detected	IDLE	ILIE	Yes	No
Parity Error	PE	PIE	Yes	No

## 15.7 SCI registers

### 15.7.1 Status register (SCISR)

SCISR Reset value: 1100 0000 (C0h)

7	6	5	4	3	2	1	0
TDRE	TC	RDRF	IDLE	OR	NF	FE	PE
RO	RO	RO	RO	RO	RO	RO	RO

**Table 72. SCISR register description**

Bit	Name	Function
7	TDRE	<p><i>Transmit data register empty</i></p> <p>This bit is set by hardware when the content of the TDR register has been transferred into the shift register. An interrupt is generated if the TIE bit = 1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a write to the SCIDR register).</p> <p>0: Data is not transferred to the shift register 1: Data is transferred to the shift register</p> <p><i>Note: Data is not transferred to the shift register unless the TDRE bit is cleared.</i></p>
6	TC	<p><i>Transmission complete</i></p> <p>This bit is set by hardware when transmission of a frame containing Data is complete. An interrupt is generated if TCIE = 1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a write to the SCIDR register).</p> <p>0: Transmission is not complete 1: Transmission is complete</p> <p><i>Note: TC is not set after the transmission of a Preamble or a Break.</i></p>
5	RDRF	<p><i>Received data ready flag</i></p> <p>This bit is set by hardware when the content of the RDR register has been transferred to the SCIDR register. An interrupt is generated if RIE = 1 in the SCICR2 register. It is cleared by a software sequence (an access to the SCISR register followed by a read to the SCIDR register).</p> <p>0: Data is not received 1: Received data is ready to be read</p>

## 16.4 Functional description

Refer to the CR, SR1 and SR2 registers in [Section 16.7](#) for the bit definitions.

By default the I<sup>2</sup>C interface operates in Slave mode (M/SL bit is cleared) except when it initiates a transmit or receive sequence.

First the interface frequency must be configured using the FRi bits in the OAR2 register.

### 16.4.1 Slave mode

As soon as a start condition is detected, the address is received from the SDA line and sent to the shift register; then it is compared with the address of the interface or the General Call address (if selected by software).

*Note:* In 10-bit addressing mode, the comparison includes the header sequence (11110xx0) and the two most significant bits of the address.

**Header matched** (10-bit mode only): The interface generates an acknowledge pulse if the ACK bit is set.

**Address not matched:** The interface ignores it and waits for another Start condition.

**Address matched:** The interface generates in sequence:

- an acknowledge pulse if the ACK bit is set
- EVF and ADSL bits are set with an interrupt if the ITE bit is set.

Then the interface waits for a read of the SR1 register, **holding the SCL line low** (see [Figure 68: Transfer sequencing EV1](#)).

Next, in 7-bit mode read the DR register to determine from the least significant bit (Data Direction Bit) if the slave must enter Receiver or Transmitter mode.

In 10-bit mode, after receiving the address sequence the slave is always in receive mode. It will enter transmit mode on receiving a repeated Start condition followed by the header sequence with matching address bits and the least significant bit set (11110xx1).

#### Slave receiver

Following the address reception and after the SR1 register has been read, the slave receives bytes from the SDA line into the DR register via the internal shift register. After each byte the interface generates in sequence:

- an acknowledge pulse if the ACK bit is set
- EVF and BTF bits are set with an interrupt if the ITE bit is set.

Then the interface waits for a read of the SR1 register followed by a read of the DR register, **holding the SCL line low** (see [Figure 68: Transfer sequencing EV2](#)).

#### Slave transmitter

Following the address reception and after SR1 register has been read, the slave sends bytes from the DR register to the SDA line via the internal shift register.

The slave waits for a read of the SR1 register followed by a write in the DR register, **holding the SCL line low** (see [Figure 68: Transfer sequencing EV3](#)).

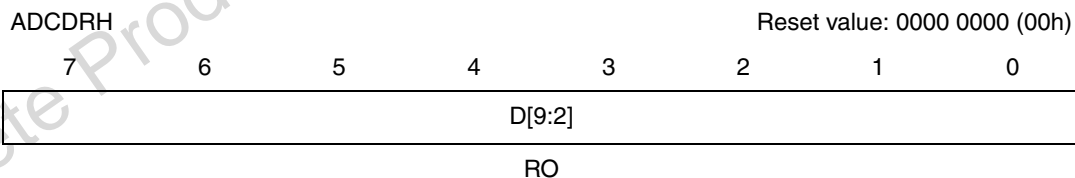
When the acknowledge pulse is received:

- The EVF and BTF bits are set by hardware with an interrupt if the ITE bit is set.

**Table 91. ADCCSR register description (continued)**

Bit	Name	Function
5	ADON	<i>A/D Converter on</i> This bit is set and cleared by software. 0: Disable ADC and stop conversion 1: Enable ADC and start conversion
4	-	Reserved. Must be kept cleared
3:0	CH[3:0]	<i>Channel Selection</i> These bits are set and cleared by software. They select the analog input to convert. 0000: Channel pin = AIN0 0001: Channel pin = AIN1 0010: Channel pin = AIN2 0011: Channel pin = AIN3 0100: Channel pin = AIN4 0101: Channel pin = AIN5 0110: Channel pin = AIN6 0111: Channel pin = AIN7 1000: Channel pin = AIN8 1001: Channel pin = AIN9 1010: Channel pin = AIN10 1011: Channel pin = AIN11 1100: Channel pin = AIN12 1101: Channel pin = AIN13 1110: Channel pin = AIN14 1111: Channel pin = AIN15  <i>Note: The number of channels is device dependent. Refer to the device pinout description.</i>

**17.6.2 Data register (ADCDRH)**



**Table 92. ADCDRH register description**

Bit	Name	Function
7:0	D[9:2]	<i>MSB of Converted Analog Value</i>

## 19 Electrical characteristics

### 19.1 Parameter conditions

Unless otherwise specified, all voltages are referred to  $V_{SS}$ .

#### 19.1.1 Minimum and maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at  $T_A = 25^\circ\text{C}$  and  $T_A = T_{Amax}$  (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean  $\pm 3\sigma$ ).

#### 19.1.2 Typical values

Unless otherwise specified, typical data is based on  $T_A = 25^\circ\text{C}$ ,  $V_{DD} = 5\text{V}$ . The typical values are given only as design guidelines and are not tested.

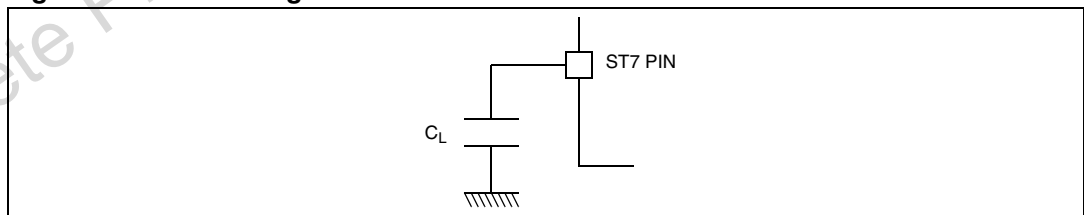
#### 19.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

#### 19.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in [Figure 71](#).

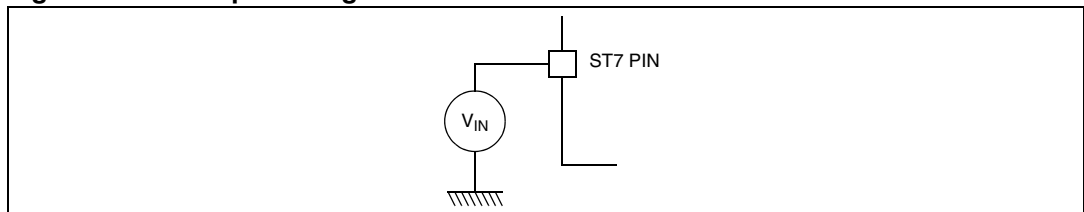
**Figure 71. Pin loading conditions**



#### 19.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in [Figure 72](#).

**Figure 72. Pin input voltage**



### 19.4.2 Supply and clock managers

The previous current consumption specified for the ST7 functional operating modes over temperature range does not take into account the clock source current consumption. To obtain the total device consumption, the two current values must be added (except for Halt mode).

**Table 111. Oscillators, PLL and LVD current consumption**

Symbol	Parameter	Conditions	Typ	Max	Unit
$I_{DD(RCINT)}$	Supply current of internal RC oscillator		625		μA
$I_{DD(RES)}$	Supply current of resonator oscillator <sup>(1)(2)</sup>		see <a href="#">section 19.5.3 on page 196</a>		
$I_{DD(PLL)}$	PLL supply current	$V_{DD} = 5V$	360		
$I_{DD(LVD)}$	LVD supply current		150	300	

1. Data based on characterization results done with the external components specified in [Section 19.5.3](#), not tested in production
2. As the oscillator is based on a current source, the consumption does not depend on the voltage.

## 19.5 Clock and timing characteristics

Subject to general operating conditions for  $V_{DD}$ ,  $f_{CPU}$ , and  $T_A$ .

### 19.5.1 General timings

Table 113. General timings

Symbol	Parameter	Conditions	Min	Typ <sup>(1)</sup>	Max	Unit
$t_{c(INST)}$	Instruction cycle time		2	3	12	$t_{CPU}$
		$f_{CPU} = 8 \text{ MHz}$	250	375	1500	ns
$t_{v(IT)}$	Interrupt reaction time <sup>(2)</sup> $t_{v(IT)} = \Delta t_{c(INST)} + 10$		10		22	$t_{CPU}$
		$f_{CPU} = 8 \text{ MHz}$	1.25		2.75	$\mu\text{s}$

1. Data based on typical application software.
2. Time measured between interrupt event and interrupt vector fetch.  $\Delta t_{c(INST)}$  is the number of  $t_{CPU}$  cycles needed to finish the current instruction execution.

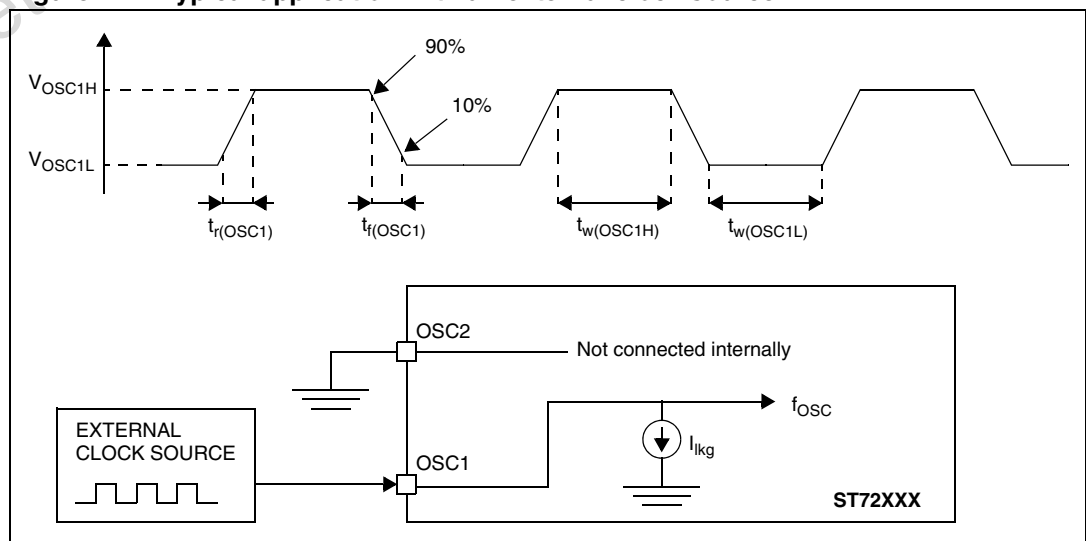
### 19.5.2 External clock source

Table 114. External clock source

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{OSC1H}$	OSC1 input pin high level voltage	See <a href="#">Figure 74</a>	$0.7 \times V_{DD}$		$V_{DD}$	V
$V_{OSC1L}$	OSC1 input pin low level voltage		$V_{SS}$		$0.3 \times V_{DD}$	
$t_{w(OSC1H)}$ $t_{w(OSC1L)}$	OSC1 high or low time <sup>(1)</sup>		5			ns
$t_r(OSC1)$ $t_f(OSC1)$	OSC1 rise or fall time <sup>(1)</sup>				15	
$I_{lkg}$	OSC1 input leakage current	$V_{SS} \leq V_{IN} \leq V_{DD}$			$\pm 1$	$\mu\text{A}$

1. Data based on design simulation and/or technology characteristics, not tested in production.

Figure 74. Typical application with an external clock source





*Note:* To reduce disturbance to the RC oscillator, it is recommended to place decoupling capacitors between  $V_{DD}$  and  $V_{SS}$  as shown in [Figure 97](#).

Obsolete Product(s) - Obsolete Product(s)

## 19.6 Memory characteristics

### 19.6.1 RAM and hardware registers

Table 119. RAM supply voltage

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RM}$	Data retention mode <sup>(1)</sup>	Halt mode (or RESET)	1.6			V

1. Minimum  $V_{DD}$  supply voltage without losing data stored in RAM (in Halt mode or under RESET) or in hardware registers (only in Halt mode). Not tested in production.

### 19.6.2 Flash memory

Table 120. Dual voltage HDFlash memory

Symbol	Parameter	Conditions	Min <sup>(1)</sup>	Typ	Max <sup>(1)</sup>	Unit
$f_{CPU}$	Operating frequency	Read mode	0		8	MHz
		Write / Erase mode	1		8	
$V_{PP}$	Programming voltage <sup>(2)</sup>	$4.5V \leq V_{DD} \leq 5.5V$	11.4		12.6	V
$I_{DD}$	Supply current <sup>(3)</sup>	Run mode ( $f_{CPU} = 4$ MHz)			3	mA
		Write / Erase		0		
		Power down mode / HALT		1	10	$\mu A$
$I_{PP}$	$V_{PP}$ current <sup>(3)</sup>	Read ( $V_{PP} = 12V$ )			200	$\mu A$
		Write / Erase			30	mA
$t_{VPP}$	Internal $V_{PP}$ stabilization time			10		$\mu s$
$t_{RET}$	Data retention	$T_A = 55^\circ C$	20			years
$N_{RW}$	Write erase cycles	$T_A = 85^\circ C$	100			cycles
$T_{PROG}$ $T_{ERASE}$	Programming or erasing temperature range		-40	25	85	$^\circ C$

1. Data based on characterization results, not tested in production
2.  $V_{PP}$  must be applied only during the programming or erasing operation and not permanently for reliability reasons.
3. Data based on simulation results, not tested in production

---

**Warning: Do not connect 12V to  $V_{PP}$  before  $V_{DD}$  is powered on, as this may damage the device.**

---

## 19.8 I/O port pin characteristics

### 19.8.1 General characteristics

Subject to general operating conditions for  $V_{DD}$ ,  $f_{OSC}$ , and  $T_A$  unless otherwise specified.

**Table 125. I/O port pin general characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IL}$	Input low level voltage <sup>(1)</sup>	CMOS ports			$0.3 \times V_{DD}$	V
$V_{IH}$	Input high level voltage <sup>(1)</sup>		$0.7 \times V_{DD}$			
$V_{hys}$	Schmitt trigger voltage hysteresis <sup>(2)</sup>			0.7		
$I_{INJ(PIN)}$ <sup>(3)</sup>	Injected current on PC6 pin (Flash devices only)	$V_{DD} = 5V$	0		+4	mA
	Injected current on an I/O pin				±4	
$\Sigma I_{INJ(PIN)}$ <sup>(3)</sup>	Total injected current (sum of all I/O and control pins)					
$I_{lkg}$	Input leakage current	$V_{SS} \leq V_{IN} \leq V_{DD}$			±1	μA
$I_S$	Static current consumption	Floating input mode <sup>(4)(5)</sup>		400		
$R_{PU}$	Weak pull-up equivalent resistor <sup>(6)</sup>	$V_{IN} = V_{SS}$   $V_{DD} = 5V$	50	120	250	kΩ
$C_{IO}$	I/O pin capacitance			5		pF
$t_{f(I/O)out}$	Output high to low level fall time <sup>(1)</sup>	$C_L = 50pF$ Between 10% and 90%		25		ns
$t_{r(I/O)out}$	Output low to high level rise time <sup>(1)</sup>			25		
$t_{w(IT)in}$	External interrupt pulse time <sup>(7)</sup>		1			$t_{CPU}$

1. Data based on characterization results, not tested in production.
2. Hysteresis voltage between Schmitt trigger switching levels. Based on characterization results, not tested.
3. When the current limitation is not possible, the  $V_{IN}$  maximum must be respected, otherwise refer to  $I_{INJ(PIN)}$  specification. A positive injection is induced by  $V_{IN} > V_{DD}$  while a negative injection is induced by  $V_{IN} < V_{SS}$ . Refer to [Section 19.2.2: Current characteristics](#) for more details.
4. Static peak current value taken at a fixed  $V_{IN}$  value, based on design simulation and technology characteristics, not tested in production. This value depends on  $V_{DD}$  and temperature values.
5. The Schmitt trigger that is connected to every I/O port is disabled for analog inputs only when ADON bit is ON and the particular ADC channel is selected (with port configured in input floating mode). When the ADON bit is OFF, static current consumption may result. This can be avoided by keeping the input voltage of this pin close to  $V_{DD}$  or  $V_{SS}$ .
6. The  $R_{PU}$  pull-up equivalent resistor is based on a resistive transistor (corresponding  $I_{PU}$  current characteristics described in [Figure 80](#)).
7. To generate an external interrupt, a minimum pulse width has to be applied on an I/O port pin configured as an external interrupt source.

### 19.11.2 I<sup>2</sup>C - inter IC control interface

Subject to general operating conditions for  $V_{DD}$ ,  $f_{CPU}$ , and  $T_A$  unless otherwise specified.

Refer to [Section 19.8: I/O port pin characteristics](#) for more details on the input/output alternate function characteristics (SDAI and SCLI). The ST7 I2C interface meets the requirements of the standard I2C communication protocol described in the following table.

**Table 132. I<sup>2</sup>C control interface characteristics**

Symbol	Parameter	Standard mode I <sup>2</sup> C		Fast mode I <sup>2</sup> C <sup>(1)</sup>		Unit	
		Min <sup>(2)</sup>	Max <sup>(2)</sup>	Min <sup>(2)</sup>	Max <sup>(2)</sup>		
$t_{w(SCLL)}$	SCL clock low time	4.7		1.3		$\mu s$	
$t_{w(SCLH)}$	SCL clock high time	4.0		0.6			
$t_{su(SDA)}$	SDA setup time	250		100		ns	
$t_h(SDA)$	SDA data hold time	0 <sup>(3)</sup>		0 <sup>(4)</sup>	900 <sup>(3)</sup>		
$t_r(SDA)$ $t_r(SCL)$	SDA and SCL rise time		1000	20+0.1C <sub>b</sub>	300		
$t_f(SDA)$ $t_f(SCL)$	SDA and SCL fall time		300				
$t_h(STA)$	START condition hold time	4.0		0.6		$\mu s$	
$t_{su(STA)}$	Repeated START condition setup time	4.7					
$t_{su(STO)}$	STOP condition setup time	4.0					
$t_w(STO:STA)$	STOP to START condition time (bus free)	4.7		1.3			
C <sub>b</sub>	Capacitive load for each bus line		400		400	pF	

- At 4 MHz  $f_{CPU}$ , maximum I<sup>2</sup>C speed (400 kHz) is not achievable. In this case, maximum I<sup>2</sup>C speed will be approximately 260 kHz.
- Data based on standard I<sup>2</sup>C protocol requirement, not tested in production.
- The maximum hold time of the START condition has only to be met if the interface does not stretch the low period of SCL signal.
- The device must internally provide a hold time of at least 300ns for the SDA signal in order to bridge the undefined region of the falling edge of SCL.

### 22.1.3 Clearing active interrupts outside interrupt routine

When an active interrupt request occurs at the same time as the related flag is being cleared, an unwanted reset may occur.

*Note:* Clearing the related interrupt mask will not generate an unwanted reset.

#### Concurrent interrupt context

The symptom does not occur when the interrupts are handled normally, that is, when:

- The interrupt flag is cleared within its own interrupt routine
- The interrupt flag is cleared within any interrupt routine
- The interrupt flag is cleared in any part of the code while this interrupt is disabled

If these conditions are not met, the symptom can be avoided by implementing the following sequence:

Perform SIM and RIM operation before and after resetting an active interrupt request.

Example:

```
SIM
Reset interrupt flag
RIM
```

#### Nested interrupt context

The symptom does not occur when the interrupts are handled normally, that is, when:

- The interrupt flag is cleared within its own interrupt routine
- The interrupt flag is cleared within any interrupt routine with higher or identical priority level
- The interrupt flag is cleared in any part of the code while this interrupt is disabled

If these conditions are not met, the symptom can be avoided by implementing the following sequence:

```
PUSH CC
SIM
Reset interrupt flag
POP CC
```